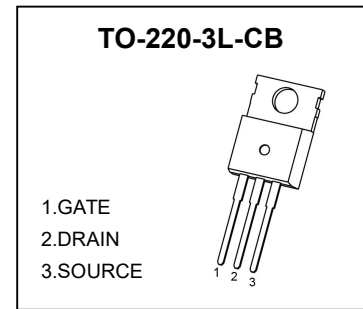


**TO-220-3L-CB Plastic-Encapsulate MOSFET**

**CJP039SN25MK** N-Channel Power MOSFET

**Key Performance Parameters**

<b>V<sub>BR(DSS)</sub></b>	<b>R<sub>DS(on)</sub>TYP</b>	<b>I<sub>D</sub></b>
<b>250V</b>	<b>33mΩ@10V</b>	<b>55A</b>



**DESCRIPTION**

The N-Channel enhancement mode power field effect transistors is using SGT technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

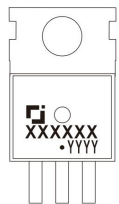
**FEATURES**

- 100% Avalanche tested
- Low drain-source on-resistance
- Low gate charge
- High current capability

**APPLICATIONS**

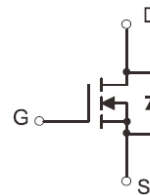
- DC/DC
- Switching application

**MARKING**



XXXXXX = 039SN25MK  
 Solid dot = Green molding compound device.  
 YYYY = Code.

**EQUIVALENT CIRCUIT**



**ABSOLUTE MAXIMUM RATINGS ( T<sub>J</sub>=25°C unless otherwise specified )**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	250	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current	I <sub>D</sub>	T <sub>C</sub> = 25°C	55
		T <sub>C</sub> = 100°C	35
Pulsed Drain Current	I <sub>DM</sub> <sup>①②</sup>	220	A
Continuous Drain Current	I <sub>D</sub>	T <sub>A</sub> = 25°C	4.6
		T <sub>A</sub> = 75°C	3.5
Avalanche Current	I <sub>AS</sub> <sup>③</sup>	17	A
Single Pulsed Avalanche Energy	E <sub>AS</sub> <sup>③</sup>	72	mJ
Power Dissipation	P <sub>D</sub> <sup>①</sup>	313	W
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150	°C

**Thermal Characteristics**

Parameter	Symbol	Value		Unit
		Typ	Max	
Thermal Resistance from Junction to Case	R <sub>θJC</sub>	0.27	0.40	°C/W
Thermal Resistance from Junction to Ambient	R <sub>θJA</sub> <sup>⑥</sup>	45	60	°C/W

# PDFNWB5×6-8L Tape and Reel

## ELECTRICAL CHARACTERISTICS (T<sub>J</sub>=25°C unless otherwise specified)

### Static Characteristics

Parameter	Symbol	Test Condition	Value			Unit	
			Min	Typ	Max		
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	250	-	-	V	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =250V, V <sub>GS</sub> =0V	T <sub>J</sub> =25°C	-	-	1.0	μA
			T <sub>J</sub> =125°C	-	-	100	
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA	
Gate-threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	3.0	4.0	V	
Static drain-source on-state resistance	R <sub>DS(on)</sub> <sup>④</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	T <sub>J</sub> =25°C	-	33	39	mΩ
			T <sub>J</sub> =125°C	-	70	83	
Forward transconductance	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =20A	-	60	-	S	

### Dynamic Characteristics<sup>⑤</sup>

Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =125V, f=1MHz	-	2631	-	pF
Output capacitance	C <sub>oss</sub>		-	155	-	
Reverse transfer capacitance	C <sub>riss</sub>		-	7	-	
Gate resistance	R <sub>g</sub>	f=1MHz	-	4.6	-	Ω
Total gate charge	Q <sub>g</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =125V, I <sub>D</sub> =20A	-	33.3	-	
Gate charge at threshold	Q <sub>G(th)</sub>		-	7.5	-	
Gate-source charge	Q <sub>gs</sub>		-	11	-	
Gate-drain charge	Q <sub>gd</sub>		-	4.9	-	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> =100V, V <sub>GS</sub> =10V, I <sub>D</sub> =20A, R <sub>g</sub> =10Ω	-	25	-	ns
Turn-on rise time	t <sub>r</sub>		-	22	-	
Turn-off delay time	t <sub>d(off)</sub>		-	54	-	
Turn-off fall time	t <sub>f</sub>		-	33	-	

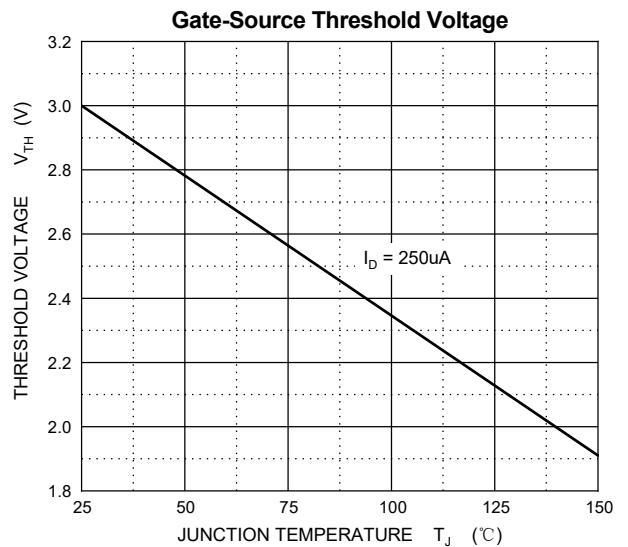
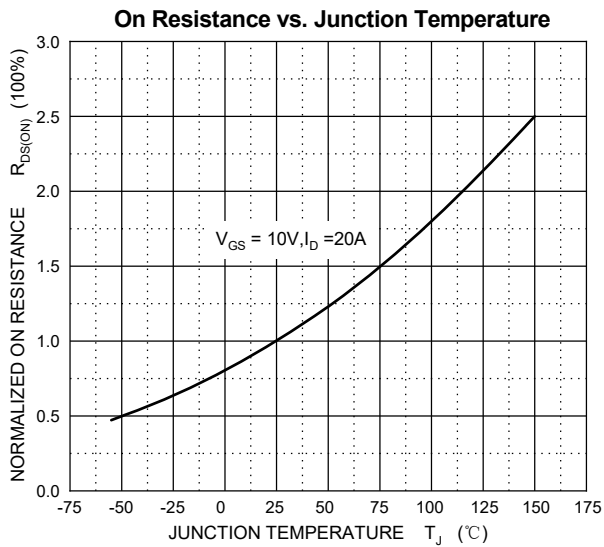
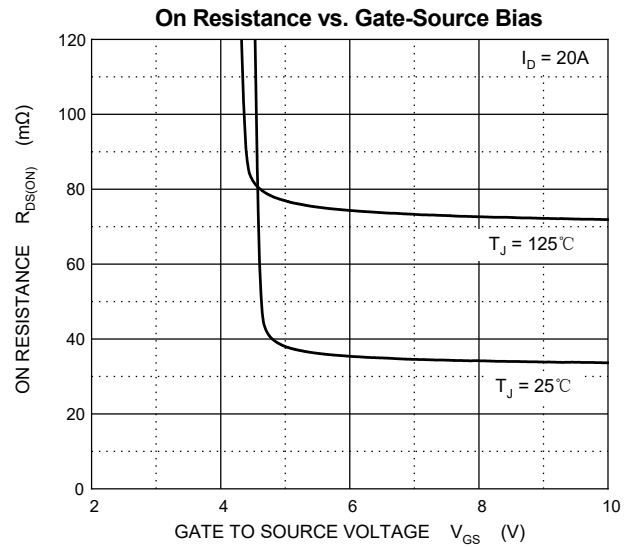
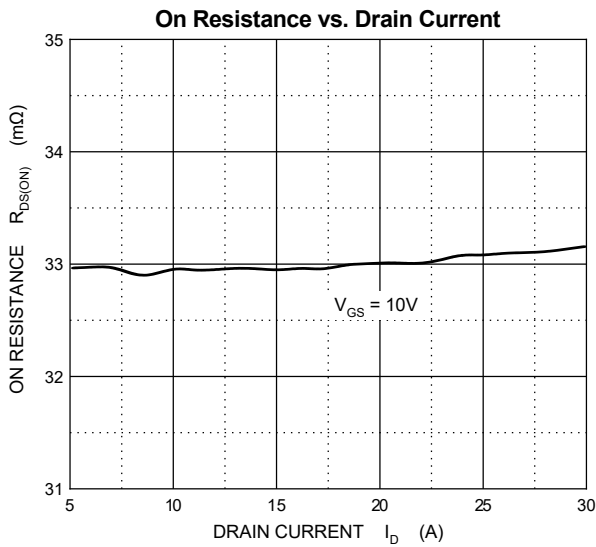
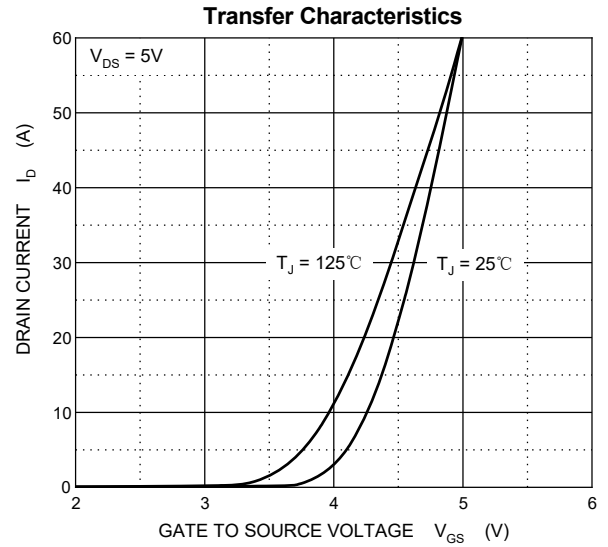
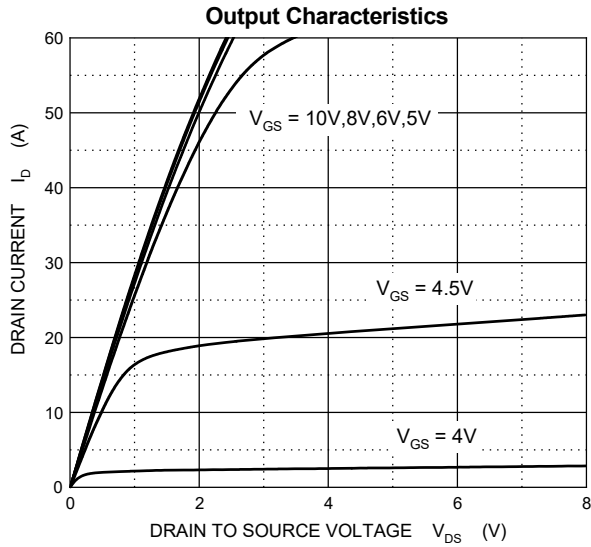
### Reverse Diode Characteristics

Drain-source diode forward voltage	V <sub>SD</sub> <sup>④</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =20A	-	-	1.2	V
Continuous drain-source diode forward current	I <sub>S</sub> <sup>①</sup>		-	-	55	A
Pulsed drain-source diode forward current	I <sub>SM</sub> <sup>①②</sup>		-	-	220	A
Reverse recovery time	t <sub>rr</sub>	V <sub>DD</sub> =100V, I <sub>S</sub> =20A,	-	140	-	ns
Reverse recovery charge	Q <sub>rr</sub>	di/dt=100A/μs	-	750	-	nC

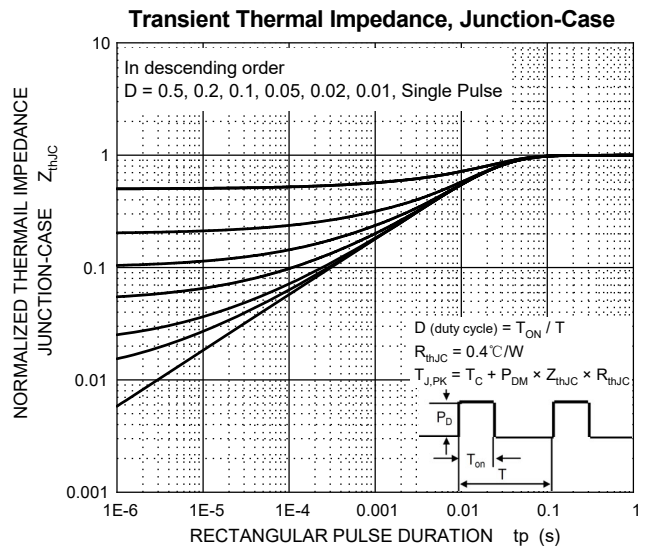
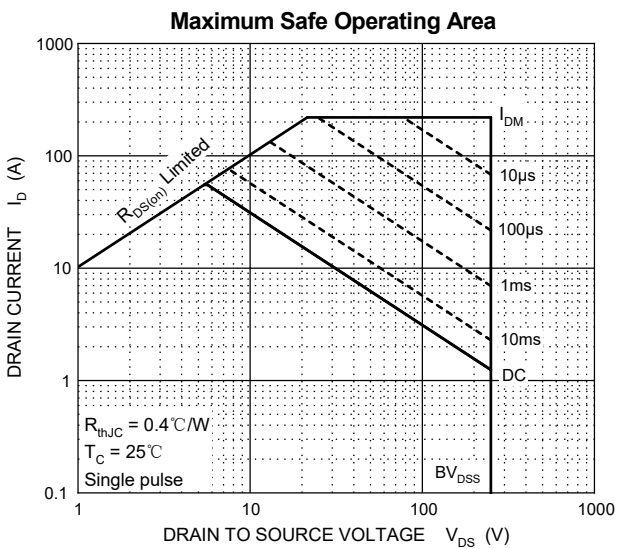
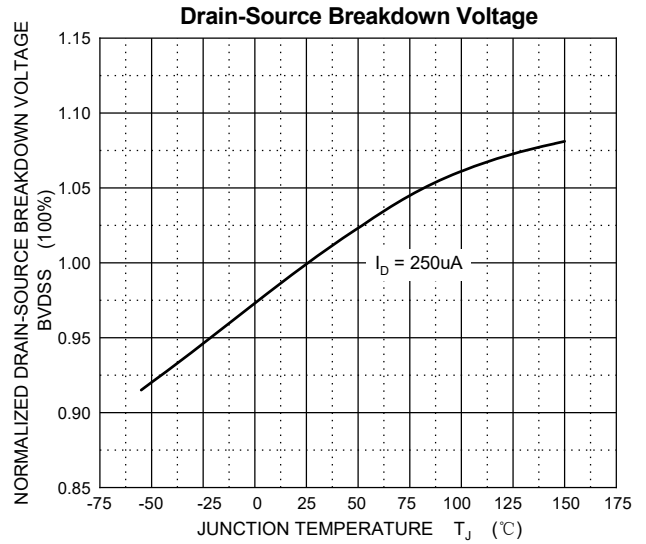
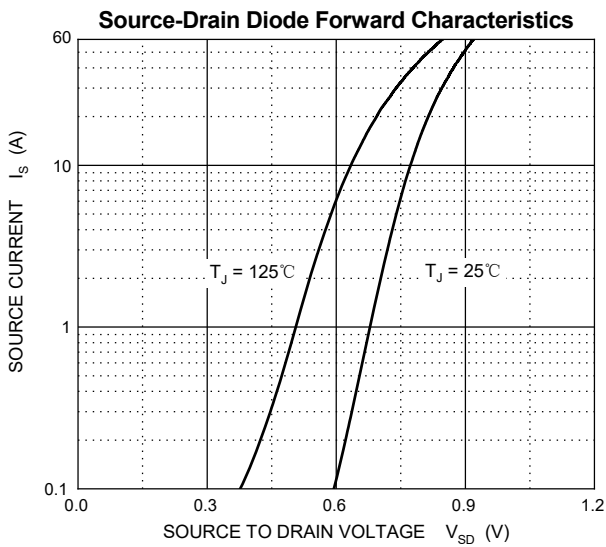
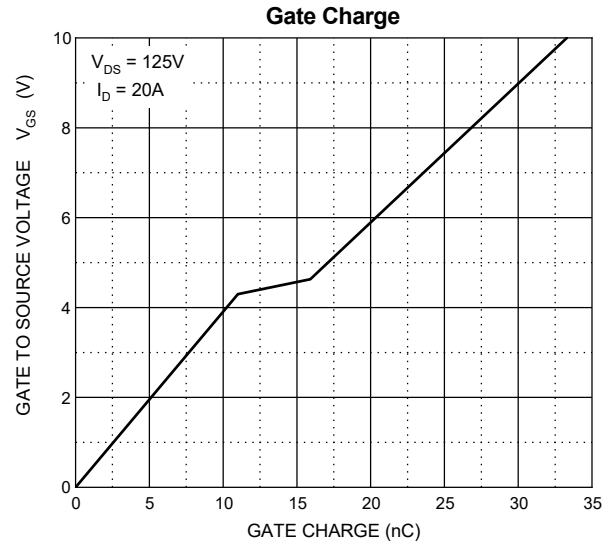
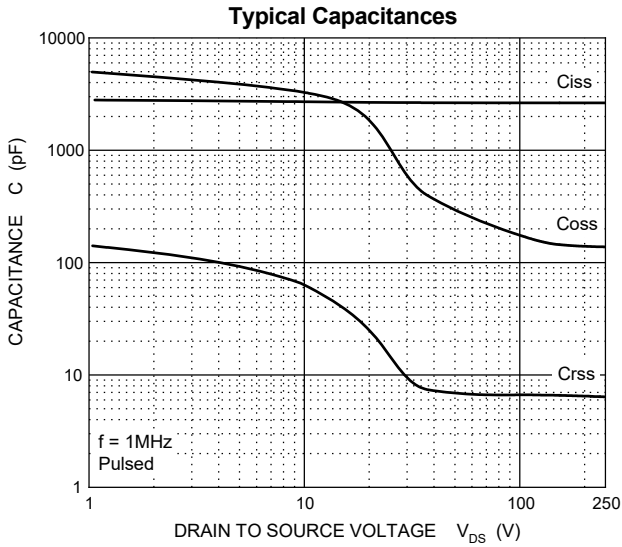
Notes:

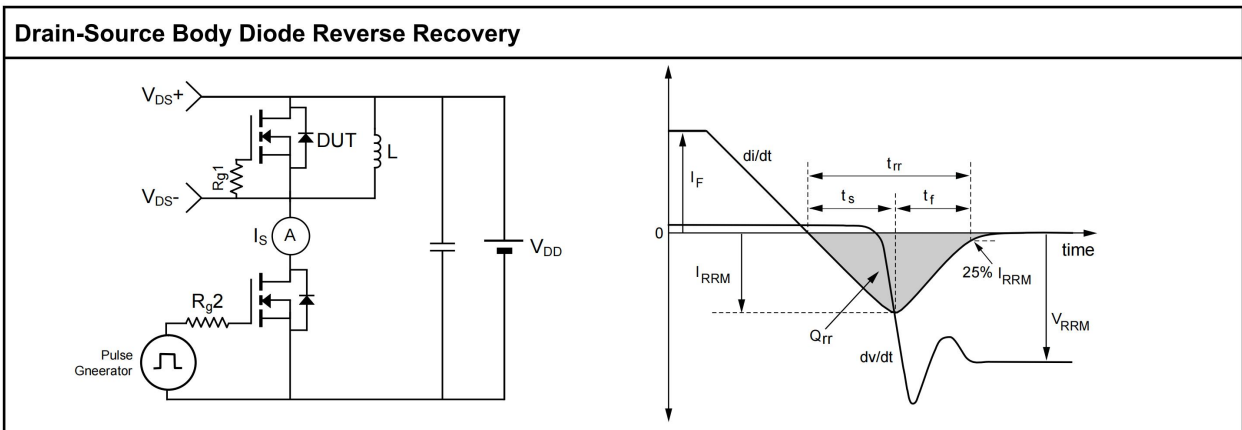
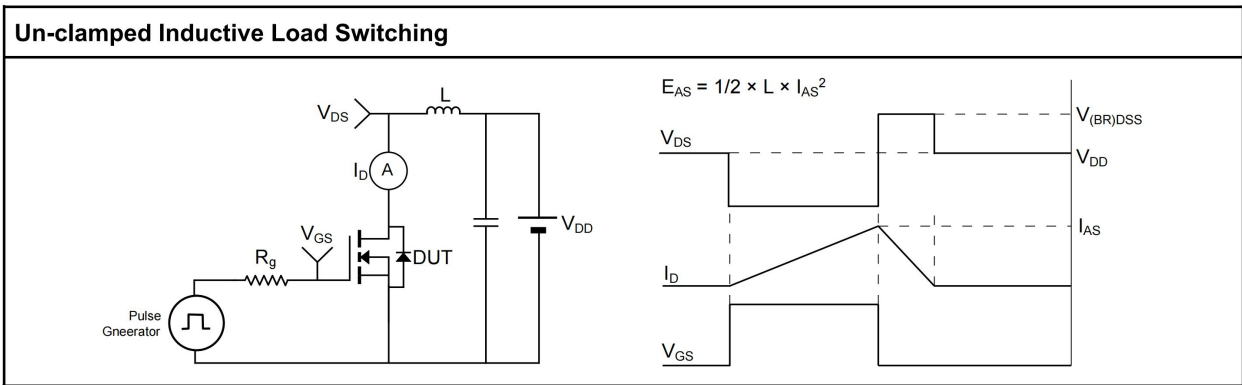
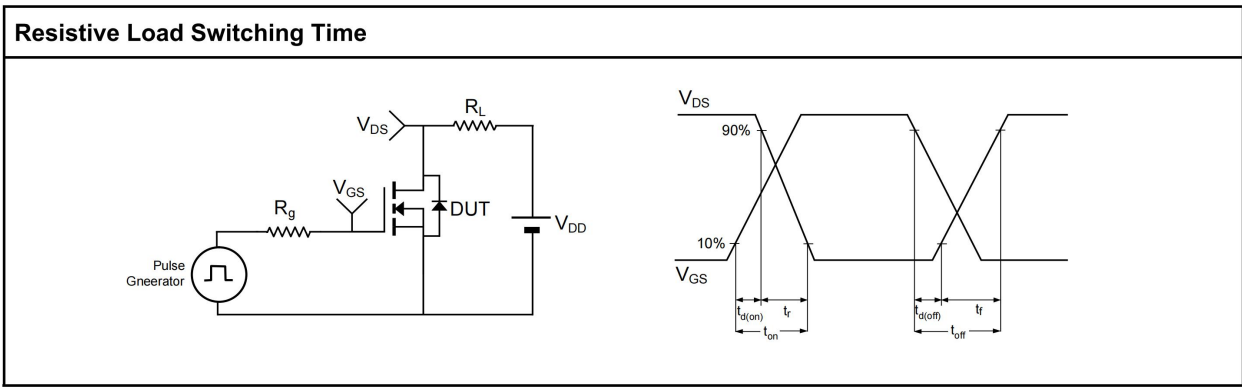
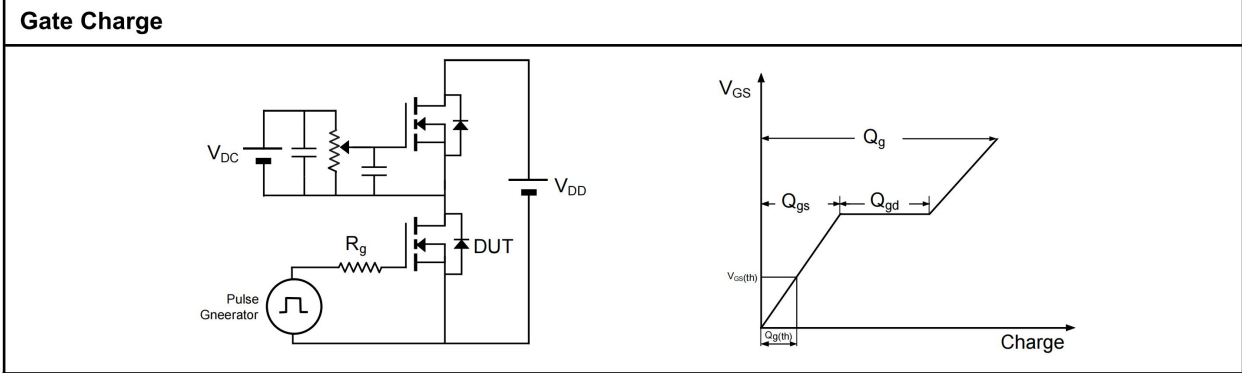
- ①.T<sub>C</sub>=25°C Limited only by maximum temperature allowed.
- ②.P<sub>W</sub>≤10μs, Duty cycle ≤1%.
- ③.EAS condition: V<sub>DD</sub>=125V, V<sub>GS</sub>=10V, L=0.5mH, R<sub>g</sub>=25Ω Starting T<sub>J</sub>=25°C.
- ④.Pulse Test : Pulse Width ≤380μs, duty cycle ≤2%.
- ⑤.Guaranteed by design, not subject to production.
- ⑥.Device mounted in a still air environment with T<sub>A</sub>=25°C.

# Typical Characteristics

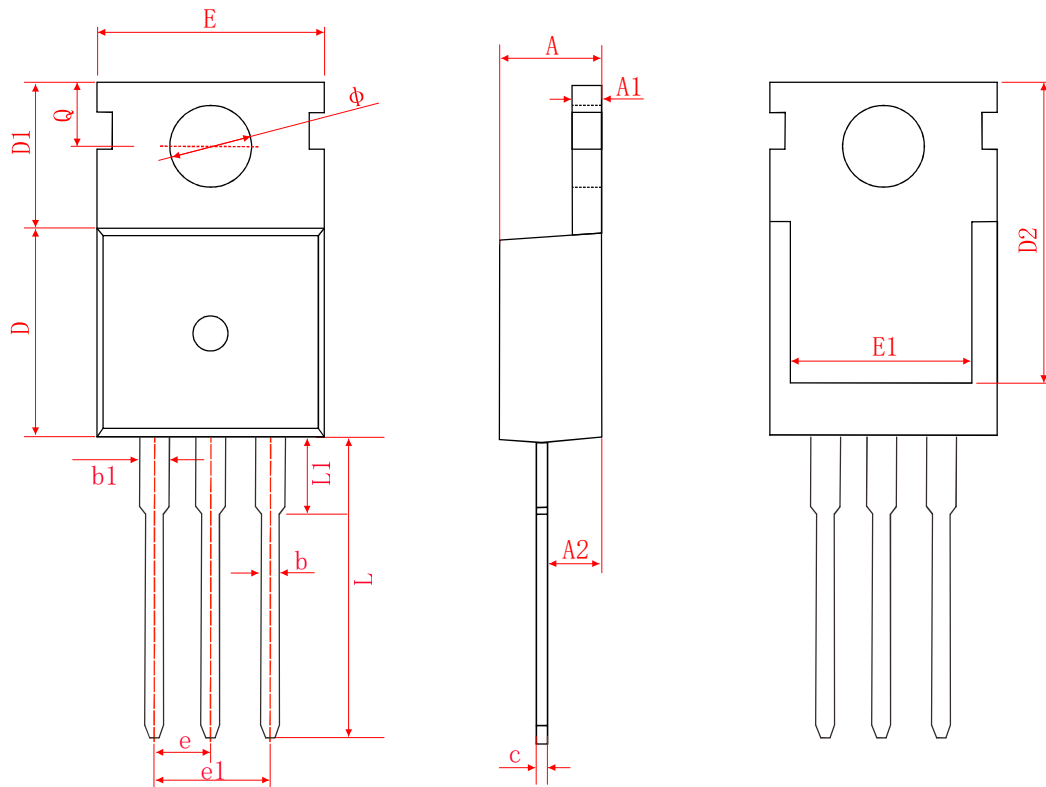


# Typical Characteristics





## TO-220-3L-CB Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.40	4.60	0.173	0.181
A1	1.25	1.35	0.049	0.053
A2	2.30	2.50	0.091	0.098
b	0.75	0.85	0.030	0.033
b1	1.25	1.42	0.049	0.056
c	0.45	0.55	0.018	0.022
D	9.10	9.30	0.358	0.366
D1	6.40	6.60	0.252	0.260
D2	13.07	13.47	0.515	0.530
e	2.54 TYP		0.100 TYP	
e1	5.08 TYP		0.200 TYP	
E	9.80	10.15	0.386	0.400
E1	7.80	8.20	0.307	0.323
Q	2.70	2.90	0.106	0.114
L	13.00	13.45	0.512	0.530
L1	-	3.40		0.134
$\Phi$	3.50	3.70	0.138	0.146